L Number	Hits	Search Text	DB	Time stamp
T Mariner	348	(438/15).CCLS.	USPAT	2004/01/12 08:08
_	258	(438/113).CCLS.	USPAT	2002/07/03 08:58
-			USPAT	2002/07/03 08:58
_	94	(438/110).CCLS.		, , , , , , , , , , , , , , , , , , , ,
-	59	(438/114).CCLS.	USPAT	2002/07/03 08:58
-	681	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
-	401		USPAT	2001/08/07 15:09
-	272		USPAT	2001/08/07 15:10
		(dice\$4 or cut\$5)		
-	901	438/15,110,113,114.ccls.	USPAT;	2002/02/04 09:53
			EPO; JPO;	E
	_		DERWENT	
-	460	438/15,110,113,114.ccls. and test\$3	USPAT;	2002/02/04 09:54
			EPO; JPO;	
			DERWENT	
-	325		USPAT;	2002/02/05 08:26
		(dic\$5 or cut\$5)	EPO; JPO;	1
			DERWENT	
-	5	(("6077757") or ("6335224") or ("6309943")	USPAT	2003/10/24 12:32
		or ("6309909") or ("6326697")).PN.		
-	7	(("6077757") or ("6335224") or ("6309943")	USPAT	2002/02/05 09:49
		or ("6309909") or ("6326697") or		
		("5858815") or ("5137836")).PN.		
_	326	(438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:28
		(dic\$5 or cut\$5)	EPO; JPO;	
		(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT	
_	. 0	((438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:33
		(dic\$5 or cut\$5) ) and (magnet\$7 adj	EPO; JPO;	
		(align\$5)	DERWENT	
_	170		USPAT;	2002/02/05 08:32
		(dic\$5 or cut\$5) ) and (align\$5)	EPO; JPO;	
		(,	DERWENT	
_	2705	magnet\$7 adj align\$5	USPAT;	2002/02/05 08:56
	2,00		EPO; JPO;	
			DERWENT	
_	0	(magnet\$7 adj align\$5) and (wafer adj20	USPAT;	2002/02/05 08:37
		dielectric adj tape)	EPO; JPO;	2002/02/03 00:3/
		distribution and cape,	DERWENT	
_		wafer adj20 dielectric adj tape	USPAT;	2002/02/05 08:37
		and the state of t	EPO; JPO;	2002/02/03 00.5/
			DERWENT	
_	0	wafer adj dielectric adj tape	USPAT;	2002/02/05 08:38
		water adj dielectric adj cape	EPO; JPO;	2002/02/03 00:30
			DERWENT	
_	248	(magnet\$7 adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
	240	(magnety, adj arrynys) and semiconductor	EPO; JPO;	2002/02/03 06.37
			DERWENT	
_	0	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:49
1		(thanged adj slot)	EPO; JPO;	2002/02/03 00.49
	·	(onarged day stoc)	DERWENT	
_	0	(magnet\$7 adj align\$5) and (charged adj	USPAT;	2002/02/05 08:49
		slot)	EPO; JPO;	2002/02/03 00:49
			DERWENT	
	613	(magnot\$7 add align\$5) and mine	USPAT;	2002/02/05 08:50
	013	(magnet\$7 adj align\$5) and ring	· ·	2002/02/03 08:30
			EPO; JPO; DERWENT	!
_	47	((magnet\$7 add align\$5) and wing) and	USPAT;	2002/02/05 08:51
_	4/	((magnet\$7 adj align\$5) and ring) and semiconductor	-	2002/02/05 08:51
		Senitconductor	EPO; JPO;	
	3000	ontically add alients	DERWENT	2002/02/05 00:56
-	3066	optically adj align\$5	USPAT;	2002/02/05 08:56
			EPO; JPO;	
	C10	/ombigo11odi	DERWENT	2002/02/05 00 57
-	612	(optically adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
	_	//HCORRECTH) /HCOOSOO4H)	DERWENT	0000/05/00 05 55
<b>_</b>	8	(("6077757") or ("6335224") or ("6309943")	USPAT	2003/06/02 08:10
		or ("6309909") or ("6326697") or		
		("5858815") or ("5137836") or		
		("4781969")).PN		
				<u></u>

-	10260	wood.inv.	USPAT;	2002/07/03 08:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	539	wood.inv. and alan	USPAT;	2002/07/03 08:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	232	(wood.inv. and alan) and (micron adj	USPAT;	2002/07/03 08:14
		technology)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		1	IBM TDB	İ
_	1	("6268650").PN.	USPAT	2002/12/20 10:24
[ <del>-</del>	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
_	331	(438/113).CCLS.	USPAT	2002/07/08 08:57
_	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
_	90	(438/114).CCLS.	USPAT	2002/07/08 08:57
_	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
_	425  - 331	(438/13).CCLS.	USPAT	2002/07/08 08:57
	140	(438/110).CCLS.	USPAT	2002/07/08 08:57
_	90	(438/114).CCLS.	USPAT	2002/07/08 08:37
	13	(("6389689") or ("5977629") or ("5796170")	1	
_	13		USPAT	2002/07/08 10:35
		or ("6326700") or ("6268650") or		
		("5858815") or ("5817535") or ("5770032") or ("4781969") or ("5073840") or		
		· · · · · · · · · · · · · · · · · · ·		
		("5696033") or ("5834839") or		
		("6160714")).PN.		0000/07/00 00 56
-	8	(("6309909") or ("5858815") or ("5137836")	USPAT	2002/07/09 09:56
		or ("6077757") or ("6326697") or		
		("6165885") or ("5834320") or		
		("4781969")).PN.		
-	0	1 (	USPAT;	2002/12/19 15:00
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
			DERWENT;	
			IBM TDB -	
_	19	wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
		(dielectric adj (layer or film))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:38
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
_	963	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
_	1212	438/15,110,113,114.ccls.	USPAT;	2002/12/19 14:38
	1212	100/10/110/110/111.0013.	US-PGPUB;	2002/12/19 14:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	0	438/15,110,113,114.ccls. and ((wafer adj	USPAT;	2002/12/19 14:40
		(bond\$3 or attach\$3) near4 (dielectric adj	US-PGPUB;	2002/12/19 14:40
			· ·	
		(layer or film))) same test\$3)	EPO; JPO;	
			DERWENT;	
		(	IBM_TDB	2002/10/02 02 12
_	9	(wafer adj (dielectric adj (layer or	USPAT;	2002/12/20 08:18
		film))) same test\$3	US-PGPUB;	]
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	13	1 , , , , , , , , , , , , , , , , , , ,	USPAT	2002/12/19 15:19
		or ("5977629") or ("6326700") or ("5817535")		
		or ("5770032") or ("5796170") or		
		("4781969") or ("5073840") or		
		("5696033")).PN.		
_	85		USPAT;	2002/12/20 08:42
		(cut\$3 or dic\$3 or slic\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	70	(wafer same dielectric same test\$3 same	IBM_TDB USPAT;	2002/12/20 09:38
-	/ 0	(cut\$3 or dic\$3 or slic\$3)) and	US-PGPUB;	2002/12/20 05.50
		semiconductor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	348		USPAT;	2002/12/20 09:35
		film))) same test\$3	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	322	((wafer same (dielectric adj (layer or	USPAT;	2002/12/20 09:38
		film))) same test\$3 ) and semiconductor	US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
_	QQ	(((wafer same (dielectric adj (layer or	IBM_TDB USPAT;	2002/12/20 09:39
	. 90	film))) same test\$3 ) and semiconductor)	US-PGPUB;	2002/12/20 03.33
		and (cut\$3 or dic\$3)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	$\frac{1}{2}$	("6424023").PN.	USPAT	2002/12/20 10:24
_	3	(("5897337") or ("5858815") or ("6389689")).PN.	USPAT	2002/12/23 11:53
_	2	(("5897337") or ("6389689")).PN.	USPAT	2002/12/23 11:53
_	9187	((balls adj grid adj arrays) or (BGA)) and	USPAT;	2003/05/20 07:59
		semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	4418	(((balls adj grid adj arrays) or (BGA))	IBM_TDB USPAT;	2003/05/20 08:02
	4410	and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	2003/03/20 00.02
		separat\$5)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4476	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/05/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or separat\$5 or saw\$4)	US-PGPUB; EPO; JPO;	
		Department of Sanya,	DERWENT;	
			IBM_TDB	
-	955		USPĀT;	2003/05/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	
		separat\$5)) and (metal adj (film or	EPO; JPO; DERWENT;	
		layer))	IBM TDB	
_	970	((((balls adj grid adj arrays) or (BGA))	USPAT;	2003/05/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	
		separat\$5 or saw\$4)) and (metal adj (film	EPO; JPO;	
		or layer))	DERWENT;	
_	1	("20010052642").PN.	IBM_TDB US-PGPUB	2003/05/20 08:12
_	472	("20010052642").PN.   wafer and (metal adj (film or layer)) and	USPAT;	2003/05/20 08:12
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)	DERWENT;	
	222	/	IBM_TDB	2004/01/12 00 00
-	233	(wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid	USPAT; US-PGPUB;	2004/01/12 08:09
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM TDB	

			T	0000 105 105
_	212	((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 08:23
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	EPO; JPO; DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)	164-106	
_	206		USPAT;	2003/05/20 09:06
	200	and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	2000,00,20 03.00
		grid adj arrays) or (BGA)) and	EPO; JPO;	
-		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6)	_	
_	1	(((wafer adj semiconductor) same (metal	USPAT;	2003/05/20 10:06
		adj (film or layer)) same (attach\$5 or	US-PGPUB;	
		bond\$4) same ((balls adj grid adj arrays)	EPO; JPO;	
		or (BGA)) same (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) same (dic\$5 or cut\$6 or	IBM_TDB	
		saw\$5)) and @ad<=20000616	_	
-	212		USPAT;	2003/05/21 09:00
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
1		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)		
-	172		USPAT;	2003/05/21 09:24
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5) ) and dic\$5		/ /
-	92		USPAT;	2003/05/21 09:35
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
	7.0	or cut\$6 or saw\$5) ) and (dicing or diced)	II O D B M -	2002 (05 (21 00 226
_	70	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:36
		and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and	US-PGPUB;	
		semiconductor and (dic\$4 or cut\$4 or	EPO; JPO; DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5) ) and (dicing or	1011-100	
		diced)) and (individual\$3 or each)		
_	70		USPAT;	2003/05/21 09:36
	/ /	and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	2003/03/21 03.30
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5) ) and (dicing or		
		diced)) and (individual\$3)		
-	6	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:37
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5) ) and (dicing or	_	
		diced)) and (individual\$3 adj device)		
-	2	,	USPAT	2004/01/12 07:56
_	241	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:10
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or ("BGA")) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM_TDB	
_	1	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/10/23 10:36
:		same (attach\$5 or bond\$4) same ((balls adj	US-PGPUB;	
		grid adj arrays) or ("BGA")) same	EPO; JPO;	
		semiconductor same (dic\$4 or cut\$4 or	DERWENT;	
	_	separat\$5))) and @ad<=20000616	IBM TDB	2002/10/04 10 25
-	2	(("6153448") or ("20020011859")).PN.	USPAT;	2003/10/24 12:35
			US-PGPUB	

	,- <u></u>			,	
-	4	(("6153448") or ("20020011859") or	USPAT;	2003/10/24	14:07
		("6064217") or ("5475317")).PN.	US-PGPUB		
-	3	(("6344401") or ("6165885") or	USPAT	2004/01/12	09:14
		("5834320")).PN.			
-	244		USPAT;	2004/01/12	08:03
:		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;		
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;		
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;		
		@ad<=20000616	IBM TDB		
_	244	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12	08:04
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;		
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;		
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;		
		@ad<=20000616	IBM_TDB		
_	166		USPAT;	2004/01/12	08:05
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;		
		grid adj arrays) or (BGA)) and	EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616 ) and	IBM_TDB		
		align\$6			
-	688	(438/455).CCLS.	USPAT:	2004/01/12	08:08
			US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
			IBM_TDB		
-	12			2004/01/12	08:11
		and (wafer and (metal adj (film or layer))	US-PGPUB;		ļ
		and (attach\$5 or bond\$4) and ((balls adj	EPO; JPO;		
		grid adj arrays) or ("BGA")) and (dic\$4 or	DERWENT;		
		cut\$4 or separat\$5)) and @ad<=20000616	IBM_TDB		
-	97		USPAT;	2004/01/12	08:52
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;		
		and ((balls adj grid adj arrays) or	EPO; JPO;		
		("BGA")) and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616	IBM_TDB		